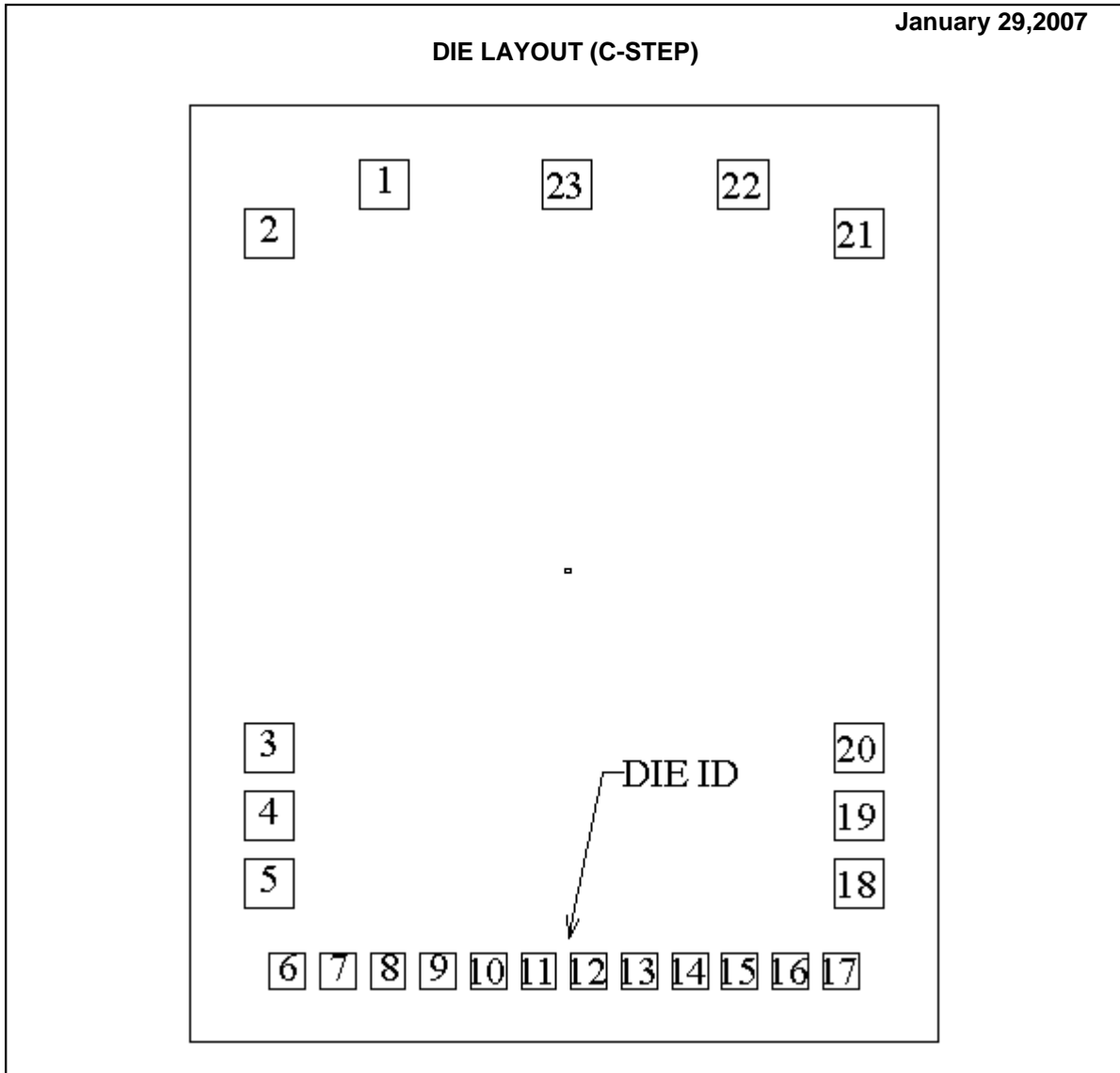


**LMC6062I MDC MWC**  
**PRECISION CMOS DUAL MICROPOWER OPERATIONAL AMPLIFIER**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LMC6062C	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1397µm x 1753µm 55.0mils x 69.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	95µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
SIGNAL NAME	PAD# NUMBER	XY COORDINATES		PAD SIZE		
		X	Y	X	Y	
OUTPUT A	1	-336	728	92	x	92
INPUT A-	2	-553	637	92	x	92
INPUT A+	3	-553	-326	92	x	92
NC	4	-553	-453	92	x	92
V-	5	-553	-580	92	x	92
NC	6	-518	-743	66	x	66
NC	7	-424	-743	66	x	66
NC	8	-330	-743	66	x	66
NC	9	-236	-743	66	x	66
NC	10	-142	-743	66	x	66
NC	11	-48	-743	66	x	66
NC	12	46	-743	66	x	66
NC	13	140	-743	66	x	66
NC	14	234	-743	66	x	66
NC	15	328	-743	66	x	66
NC	16	422	-743	66	x	66
NC	17	516	-743	66	x	66
NC	18	550	-580	92	x	92
NC	19	550	-453	92	x	92
INPUT B	20	550	-326	92	x	92
INPUT B-	21	550	637	92	x	92
OUTPUT B	22	334	728	92	x	92
V+	23	6	728	92	x	92

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